# Michael Mayer

List of Publications by Year
in descending order

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| 36 | 273 | 9 | 14 |
|---|---|---|---|
| papers | citations | h-index | g-index |

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| 37 | 37 | 37 | 138 |
|---|---|---|---|
| all docs | docs citations | times ranked | citing authors |

| # | Article | IF | Citations |
|---|---|---|---|
| 1 | In-situ Determination of Specimen Temperature during Electromigration Testing of Solder Joint. , 2021, , . | | 1 |
| 2 | SAC305 Solder Reflow: Identification of Melting and Solidification Using In-Process Resistance Monitoring. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1623-1631. | 2.5 | 10 |
| 3 | Dynamic resistance monitoring of aging process of pressureless sintered nano-silver joints. , 2019, , . | | 1 |
| 4 | The Fundamentals of Wire Bonding. , 2019, , 23-64. | | 0 |
| 5 | Effects of Epoxy Molding Compound on Electrical Resistance Degradation of Pd-Coated Cu Wire Bonds in the 175 Â°C to 225 Â°C Range. , 2018, , . | | 2 |
| 6 | Real time joint resistance monitoring during solder reflow. Journal of Alloys and Compounds, 2017, 695, 3002-3010. | 5.5 | 6 |
| 7 | Miniature environmental chambers for temperature humidity bias testing of microelectronics. Review of Scientific Instruments, 2017, 88, 034707. | 1.3 | 4 |
| 8 | Numerical Simulations of Joint-to-Joint Temperature Variation During Thermo-Compression Bonding. , 2017, , . | | 2 |
| 9 | Conductive pathway on cotton fabric created using solution with silver organometallic compound. Materials Research Express, 2017, 4, 106305. | 1.6 | 1 |
| 10 | Factors affecting activation energy for pd-coated cu ball bond resistance degradation on Al bond pads in high temperature storage. , 2017, , . | | 4 |
| 11 | The Electrical Reliability of Silver Wire Bonds under High Temperature Storage. , 2016, , . | | 4 |
| 12 | Process Design of Fine Pitch Ball Bonding by Volume Conservation Modelling. , 2016, , . | | 4 |
| 13 | Electromigration of composite Sn-Ag-Cu solder bumps. Electronic Materials Letters, 2015, 11, 1072-1077. | 2.2 | 27 |
| 14 | Sn-Ag-Cu to Cu joint current aging test and evolution of resistance and microstructure. Electronic Materials Letters, 2015, 11, 1078-1084. | 2.2 | 8 |
| 15 | Reliability testing of wire bonds using pad resistance with van der Pauw method. , 2014, , . | | 4 |
| 16 | Electromigration testing of wire bonds. , 2014, , . | | 2 |
| 17 | Analysis of the electrical characteristics and structure of Cu-Filled TSV with thermal shock test. Electronic Materials Letters, 2014, 10, 649-653. | 2.2 | 13 |
| 18 | Simulation of Ultrasonic Stress During Impact Phase in Wire Bonding. Journal of the Microelectronics and Packaging Society, 2013, 20, 7-11. | 0.1 | 1 |

| # | Article | IF | Citations |
|---|---|---|---|
| 19 | Low cost Pd coated Ag bonding wire for high quality FAB in air. , 2012, , . | | 15 |
| 20 | Low-cost Palladium coating process and its effect on free-air-ball softness and second bond strength of Cu bonding wires. , 2012, , . | | 3 |
| 21 | Golden bump for 20micron diameter wire bond enhancement at reduced process temperature. Microelectronic Engineering, 2011, 88, 3024-3029. | 2.4 | 5 |
| 22 | Ultrasonic stresses in thermosonic ball bonding. , 2011, , . | | 4 |
| 23 | A New Non-PRM Bumping Process by Electroplating on Si Die for Three Dimensional Packaging. Materials Transactions, 2010, 51, 1887-1892. | 1.2 | 11 |
| 24 | Assessing Au-Al wire bond reliability using integrated stress sensors. , 2010, , . | | 10 |
| 25 | Effect of ultrasonic capillary dynamics on the mechanics of thermosonic ball bonding. IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control, 2010, 57, 241-252. | 3.0 | 5 |
| 26 | Sn Bumping Without Photoresist Mould and Si Dice Stacking for 3-D Packaging. IEEE Transactions on Advanced Packaging, 2010, 33, 912-917. | 1.6 | 11 |
| 27 | Wire Bonding UPH and Stitch Bond Improvement using 20 Micron Diameter Insulated Wire with Security Bump. International Symposium on Microelectronics, 2010, 2010, 000667-000674. | 0.0 | 1 |
| 28 | Finite Element Modeling of Simultaneous Ultrasonic Bumping With Au Balls. Journal of Electronic Packaging, Transactions of the ASME, 2009, 131, . | 1.8 | 2 |
| 29 | Comparison of Insulated with Bare Au Bonding Wire: HAZ Length, HAZ Breaking Force, and FAB Deformability. Journal of Electronic Materials, 2009, 38, 834-842. | 2.2 | 8 |
| 30 | Low-Stress Thermosonic Copper Ball Bonding. IEEE Transactions on Electronics Packaging Manufacturing, 2009, 32, 176-184. | 1.4 | 39 |
| 31 | Online methods to measure breaking force of bonding wire using a CMOS stress sensor and a proximity sensor. Sensors and Actuators A: Physical, 2008, 148, 462-471. | 4.1 | 12 |
| 32 | Tail Breaking Force in Thermosonic Wire Bonding with Novel Bonding Wires. Materials Science Forum, 2008, 580-582, 201-204. | 0.3 | 5 |
| 33 | Microelectronic Wire Bonding with Insulated Au Wire: Effects of Process Parameters on Insulation Removal and Crescent Bonding. Materials Transactions, 2008, 49, 2347-2353. | 1.2 | 11 |
| 34 | Analysis of Ultrasonic Wire Bonding by In-situ Piezoresistive Microsensors. , 2001, , 1398-1401. | | 10 |
| 35 | Complete set of piezoresistive coefficients of CMOS -diffusion. Journal of Micromechanics and Microengineering, 1998, 8, 158-160. | 2.6 | 11 |
| 36 | Ultrasonic Friction Power in Microelectronic Wire Bonding. Materials Science Forum, 0, 539-543, 3920-3925. | 0.3 | 3 |